

SE 系列 无铅双波峰焊锡机

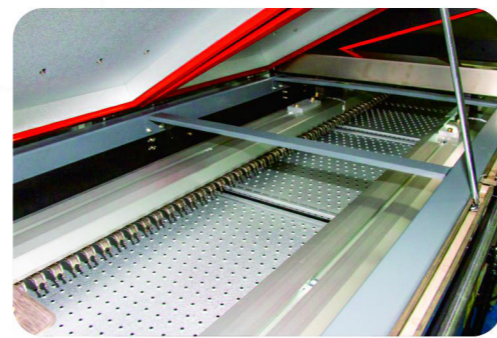
SE Series Lead-Free Dual Wave Soldering System



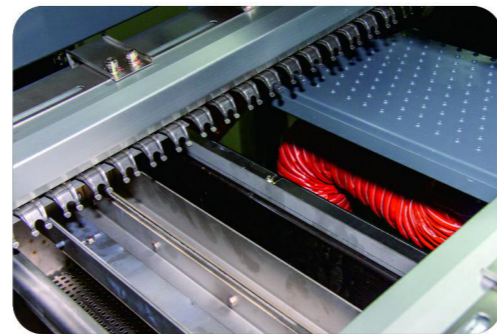
产品描述

Product Description

- 运输系统采用无级电子调整, 闭环控制, 速度稳定准确;
- 入口端设有压力辅助装置, 使PCB进入时避免打滑;
- 助剂喷头采用步进电机驱动, 保证助焊剂涂覆均匀;
- 喷雾系统模块化设计, 喷头始终垂直轨道, 保证助焊剂良好的穿透PCB;
- 强制自然风冷系统, 可满足无铅工艺对冷却斜率的要求;
- 轨道角度手动调整, 操作方便;
- 预热区采用热风加热, 温度稳定。
- Closed loop with inverter control system to keep the stability and accuracy of the conveyor speed;
- The assistant pressure device nearby the entrance to prevent the PCB from slipping;
- Spray nozzle driving by stepping motor is to make sure the coating uniformly;
- Module design of spray fluxer system and the design of nozzle always be perpendicular to rail, which can make sure the flux penetrates PCB easily;
- Forced air cooling system to attain the cold-down slope as per lead-free required;
- Conveyor angle can easily be adjusted by manual;
- Standard with hot air heating for preheating zones.



热风预热
Hot Air preheat



锡炉及冷却
Solder Pot & Cooling

- 外形流线型设计, 内部模块化设计, 适合SMT及直插元件的无铅焊接;
- 喷雾系统采用离心风机上抽风, 防止助焊剂滴到PCB上;
- 助焊剂缓衝罐感应器外置, 更加可靠耐用;
- 内置助焊剂喷头自动清洗功能系统;
- 标配冷风刀, 防止助焊剂雾气向外扩散, 减少污染;
- 双波控制采用无级变频技术, 可独立控制波峰高度;
- 1/4HP大功率波峰马达, 最大波峰高度可达15mm;
- 具有超温声光报警及紧急制动系统, 所有马达均有过载保证。
- Module design suitable for SMT & THT component soldering;
- Exhaust adopt centrifugal fan with double filters to avoid any flux drop to PCB;
- The level of flux container is controlled by non-contact sensors to ensure no Corrosion and longer life;
- Flux spray nozzle with self-cleaning system;
- Standard with air knives to prevent flux expand to preheat zone;
- Wave height control adopted with inverter, it can be set individually;
- 1/4HP high power mechanical pump to meet the wave as high as 15mm;
- Light & Sound alarm, Emergency stop and over-load protection.

设备参数

Specification

设备型号	Model No.	SE-350	SE-450
外型尺寸 (L×W×H)	Dimensions (L×W×H)	4401*1582*1735mm	4401*1582*1735mm
净重	Weight	Approx. 1800KG	
电源	Source Power	AC 380V3Φ5W 50/60Hz; 37kw (Option: AC 220V 3Φ5 50/60Hz)	
功率	Operating Power	工作功率 Operating Power ≤9KW	工作功率 Operating Power ≤10KW
预热升温时间	Preheating Time	≤ 18min	
温度范围	Temperature Range	室温 Room temperature-230°C	
PCB宽度范围	PCB Width	50~350mm	50~450mm
PCB上下空间	PCB Clearance	上 120mm/ 下 25mm top 120mm / bottom 25mm	
运输方向	Conveyor Direction	L to R (Option: R to L)	
PCB入口距地面高度	Conveyor Height	750±20 mm (Entrance)	
运输速度	Conveyor Speed	300-1800mm/min	
设备配置	Device Layout		
预热区数量及方式	Heating Zones	3 个底部热风预热	3 bottom hot air preheating zones
温控方式	Temp. Control Mode	PID+ SSR	
控制方式	Control System	PC+PLC	
喷雾系统	Spray System	步进马达 Internal Stepping motor spray	
运输爪	Conveyor Finger	滚子重型双钩爪 (承重:60KG) Heavy duty double-hook finger claw	
锡炉容量	Pot Capacity	480kg	550kg
锡炉运行方式	Pot Operation Mode	机械泵 Mechanical Pump	
炉胆材质	Pot Material	铸铁+搪瓷处理 Cast iron + Enamel processing (选配Option: 全钛)	
冷却方式	Cooling Method	强制风冷 Forced Air Cooling	

备注: 参数若有更改, 恕不另行通知! The above contents are subject to change without further notice!